

# C0603C821K3RACTU

oral Information

Aliases (C0603C821K3RAC7867) SMD Comm X7R, Ceramic, 820 pF, 10%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm



General Information	General Information		
Series	SMD Comm X7R		
Style	SMD Chip		
Description	SMD, MLCC, Temperature Stable, Class II		
Features	Temperature Stable, Class II		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	4.8 mg		
Shelf Life	78 Weeks		
MSL	1		

	Specifications	
0603	Capacitance	820 pF
1.6mm +/-0.15mm	Measurement Condition	1 kHz 1.0Vri
0.8mm +/-0.15mm	Tolerance	10%
0.8mm +/-0.07mm	Voltage DC	25 VDC
0.5mm MIN	Dielectric Withstanding Voltage	62.5 VDC
0.35mm +/-0.15mm	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with	15%, 1kHz 1.
T&R, 180mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)	
4000	Dissipation Factor	3 5% 1kHz

Dimensions Chip Size L W Т S В

### **Packaging Specifications**

Packaging Packaging Quantity

	Specifications	
	Capacitance	820 pF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	10%
	Voltage DC	25 VDC
	Dielectric Withstanding Voltage	62.5 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	Dissipation Factor	3.5%1 kHz 1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

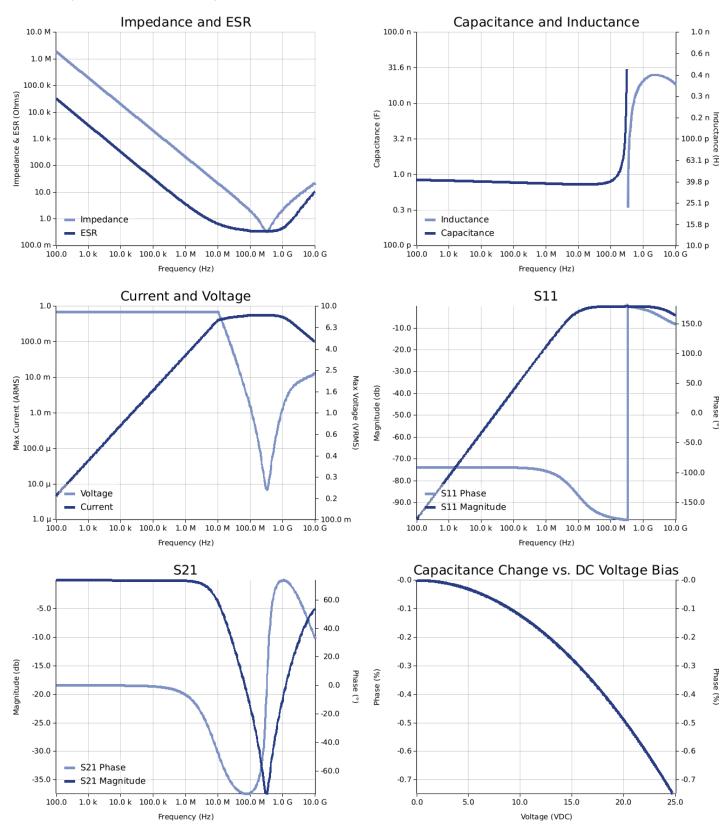
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### Simulations

For the complete simulation environment please visit Y-SIM.





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#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple Current/ Voltage Vs. Frequency plots is the ESR at ambient temperature. The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question. Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance. The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.